The 2021 IEEE International Conference on Communications (ICC 2021) will be held in the beautiful city of Montreal, QC, Canada, from 14 to 18 June 2021. Themed, "Connectivity – Security – Privacy", this flagship conference of the IEEE Communications Society will feature a comprehensive high-quality technical program including 13 symposia and a variety of tutorials and workshops. IEEE ICC 2021 will also include an attractive Industry Program aimed at industry practitioners and academia members. This program will consist of both keynotes and panels by prominent leaders in industry, academia, research, and government plus exhibits.

To be published in the IEEE ICC 2021 Conference Proceedings and IEEE Xplore®, an author of an accepted paper is required to register for the conference at the full or limited rate and the paper must be presented at the conference. Non-refundable registration fees must be paid prior to uploading the final IEEE formatted, publication-ready version of the paper. For authors with multiple accepted papers, one full or limited registration is valid for up to 3 papers.

**CALL FOR PAPERS AND PROPOSALS**

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**TECHNICAL SYMPOSIAS**
- Cognitive Radio and AI-Enabled Networks
- Communication and Information Systems Security
- Communications QoS, Reliability, and Modeling
- Communications Software and Multimedia
- Communication Theory
- Green Communication Systems and Networks
- IoT and Sensor Networks
- Mobile and Wireless Networks
- Next-Generation Networking and Internet
- Optical Networks and Systems
- Signal Processing for Communications
- Wireless Communications

**INDUSTRY FORUMS**
Proposals should be submitted to the Industry Forums and Content Co-Chairs (denis.couillard@ultra-tcs.com; rwilson@ciena.com) for reviews. Submissions are sought for Industry Forums on the latest technical and business issues in communications and networking, topics include:

**Technology:**
- 5G deployment results and roadmaps: eMBB, URLLC, and mMTC
- Future networks (6G): Core network and access technologies
- Cybersecurity
- AI & Communications
- Quantum information and sensing
- Robotics: Swarms and smart dust

**Verticals:**
- Public security
- Advanced manufacturing
- Smart grid
- Next-generation immersive entertainment
- Smart construction and buildings
- Connected health
- Smart transportation (ITS)

**Business and Regulatory Issues:**
- Technology Auditing & Regulatory
- Protecting & Sharing Intellectual Property
- Sustainability and corporate responsibility
- Smart Cities: Technology integration and regulatory issues
- Emerging entrepreneurship

**WORKSHOPS**
Submissions are sought for Workshops on the latest technical and business issues in communications and networking.

**TUTORIALS**
Proposals are invited for half- or full-day Tutorials on all communications and networking topics.

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**Important Dates**

**Industry Forum Proposals:** 30 Sept 2020
**Workshop Proposals:** 3 Aug 2020
**Tutorial Proposals:** 5 Oct 2020